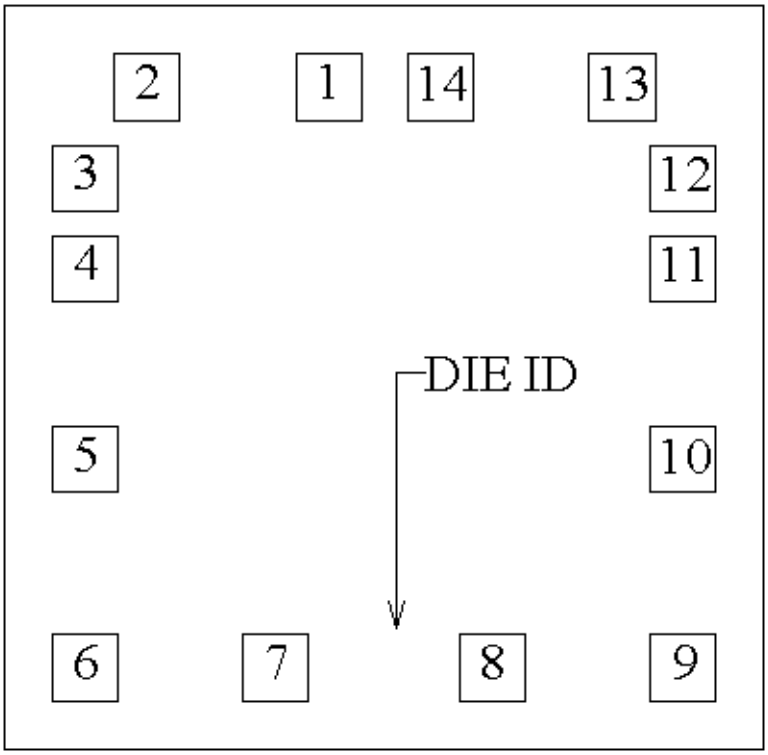
LM2901 MDA MWA
LOW POWER LOW OFFSET VOLTAGE QUAD COMPARATORS

February 25,2002

DIE LAYOUT (H-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		**General Die Information**	
Physical Die Identification	1901H	Bond Pad Opening Size (min)	92µm x 92µm
Die Step	H	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	1067µm x 1041µm 42mils x 41mils	Back Side Connection	Floating or GND
Thickness	330µm Nominal		
Min Pitch	127µm Nominal		

Special Assembly Requirements:
Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (H -Step)

(Referenced to die center, coordinates in µm) NC = No Connection

SIGNAL NAME	PAD# NUMBER	X/Y CORRDINATES X	Y	PAD SIZE X		Y
Output 2	1	-77	407	92	x	92
Output 1	2	-333	407	92	x	92
V+	3	-420	280	92	x	92
-Input 1	4	-420	153	92	x	92
+Input 1	5	-420	-115	92	x	92
-Input 2	6	-420	-407	92	x	92
+Input 2	7	-152	-407	92	x	92
-Input 3	8	152	-407	92	x	92
+Input 3	9	420	-407	92	x	92
-Input 4	10	420	-115	92	x	92
+Input 4	11	420	153	92	x	92
GND	12	420	280	92	x	92
Output 4	13	334	407	92	x	92
Output 3	14	79	407	92	x	92

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